

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
80V	9mΩ@10V	95A

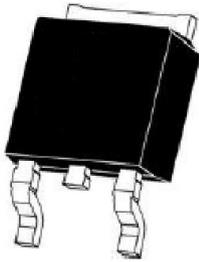
Feature

- Fast switching
- Low gate charge and $R_{ds(on)}$

Application

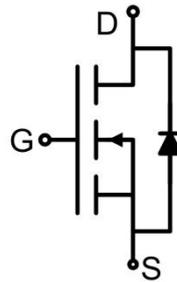
- DC-DC converter
- Power switching application
- Power Management

Package

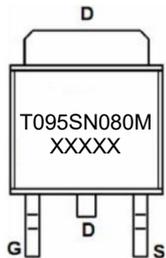


TO-252AB

Circuit diagram



Marking



Absolute maximum ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	80	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($T_C=25^\circ\text{C}$)	I_D	95	A
Continuous Drain Current ($T_C=100^\circ\text{C}$)	I_D	64	A
Pulsed Drain Current	I_{DM}	380	A
Single Pulse Avalanche Energy ¹⁾	E_{AS}	542	mJ
Power Dissipation ($T_C=25^\circ\text{C}$)	P_D	165	W
Thermal Resistance Junction to Case	$R_{\theta JC}$	0.75	$^\circ\text{C}/\text{W}$
Operating Junction Temperature	T_J	-55 ~ +150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 ~ +150	$^\circ\text{C}$

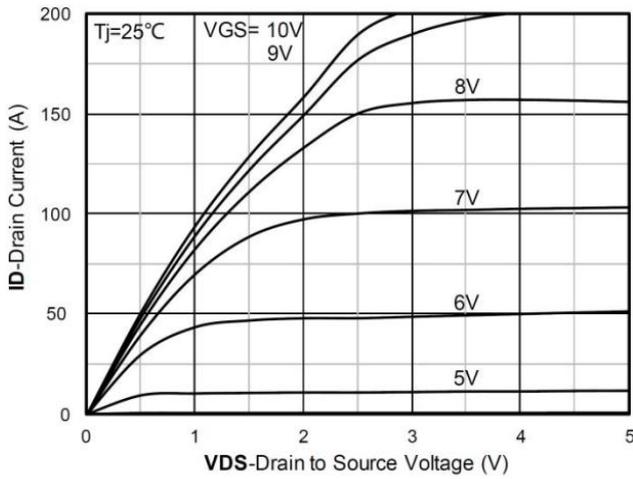
Electrical characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	80			V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 64\text{V}, V_{GS} = 0\text{V}, T_J = 25^\circ\text{C}$			1	μA
Gate-body leakage current	I_{GSS}	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$			± 100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2	3	4	V
Drain-source on-resistance	$R_{DS(on)}$	$V_{GS} = 10\text{V}, I_D = 30\text{A}$		6	9	$\text{m}\Omega$
Dynamic characteristics²⁾						
Input Capacitance	C_{iss}	$V_{DS} = 40\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$		3610		pF
Output Capacitance	C_{oss}			285		
Reverse Transfer Capacitance	C_{rss}			210		
Total Gate Charge	Q_g	$V_{DS} = 40\text{V}, V_{GS} = 10\text{V}, I_D = 30\text{A}$		108		nC
Gate-Source Charge	Q_{gs}			32		
Gate-Drain Charge	Q_{gd}			24		
Turn-on delay time	$t_{d(on)}$	$V_{DS} = 40\text{V}, V_{GS} = 10\text{V}, I_D = 30\text{A}$ $R_G = 6\Omega$		18		nS
Turn-on rise time	t_r			62		
Turn-off delay time	$t_{d(off)}$			52		
Turn-off fall time	t_f			15		
Source-Drain Diode characteristics						
Diode Forward Current	I_S				95	A
Diode Forward voltage	V_{SD}	$V_{GS} = 0\text{V}, I_S = 1\text{A}$			1.2	V
Reverse recover time	T_{rr}	$I_S = 20\text{A}, di/dt = -100\text{A}/\mu\text{s}$		37		nS
Reverse recovery charge	Q_{rr}	$T_J = 25^\circ\text{C}$		58		nC

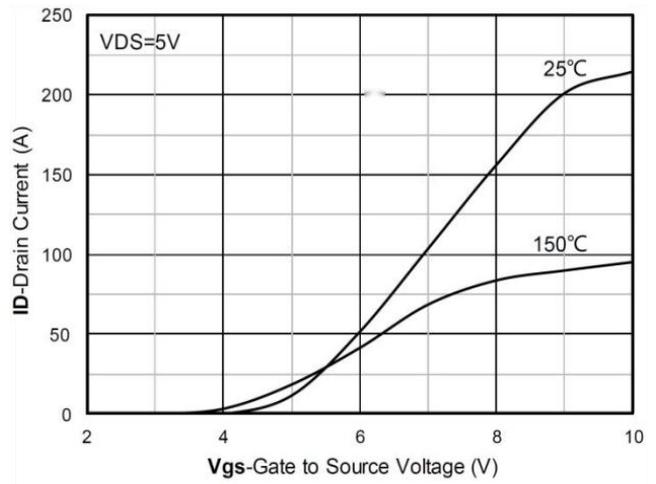
Notes:

- 1) The EAS test condition is $V_{DD} = 40\text{V}, V_{GS} = 10\text{V}, L = 0.5\text{mH}, R_G = 25\Omega$.
- 2) Guaranteed by design, not subject to production testing.

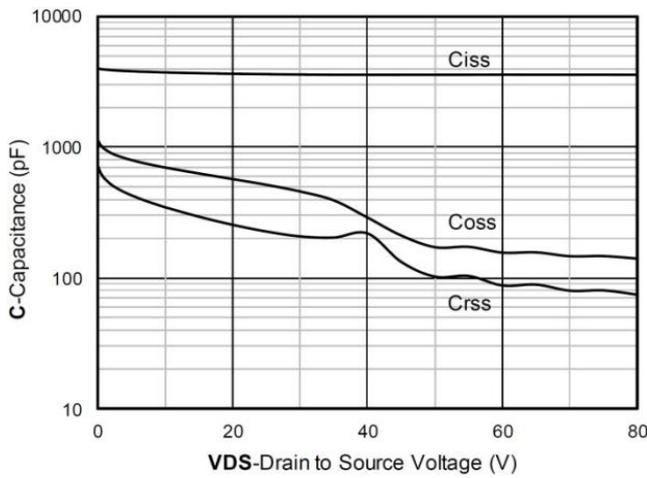
Typical Characteristics



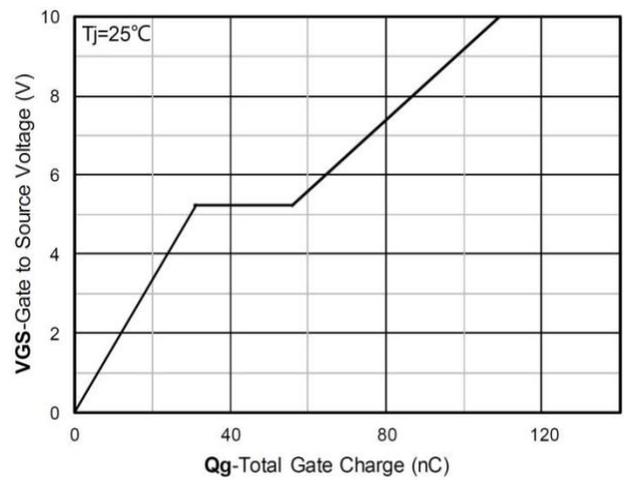
Output Characteristics



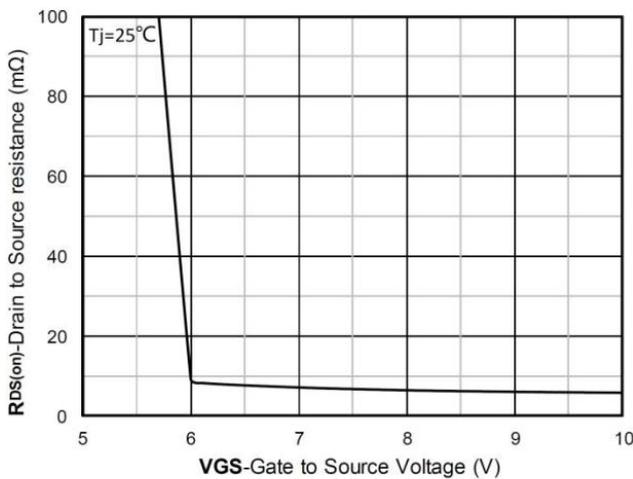
Transfer Characteristics



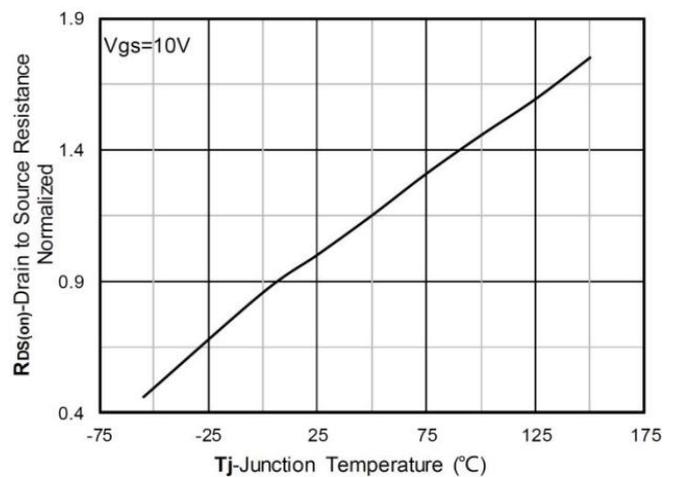
Capacitance Characteristics



Gate Charge

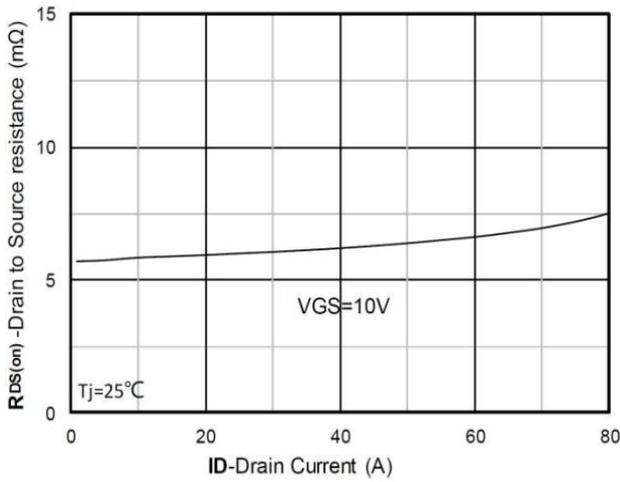


On-Resistance vs Gate to Source Voltage

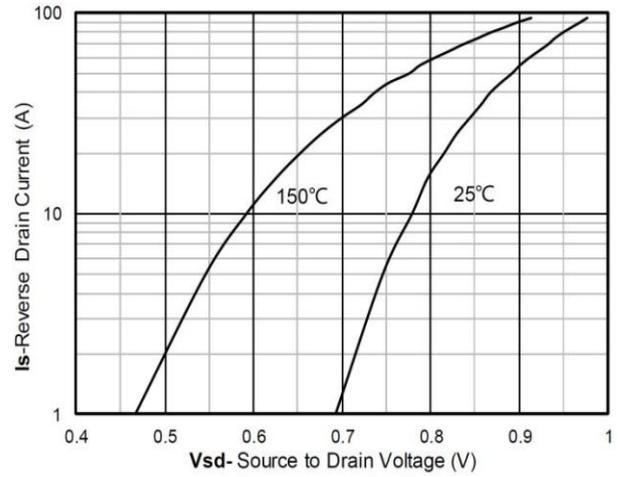


Normalized On-Resistance

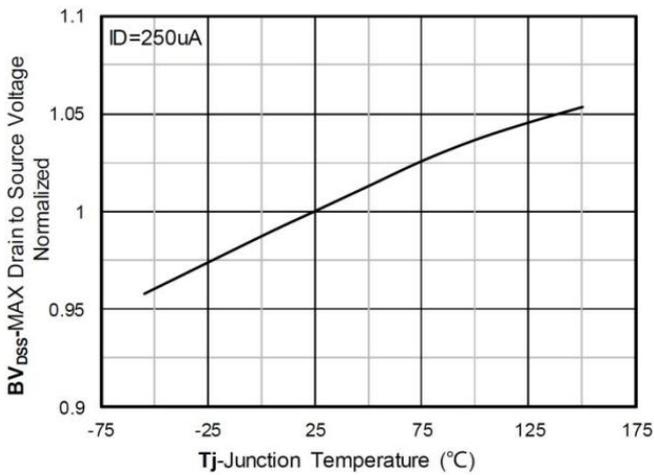
Typical Characteristics



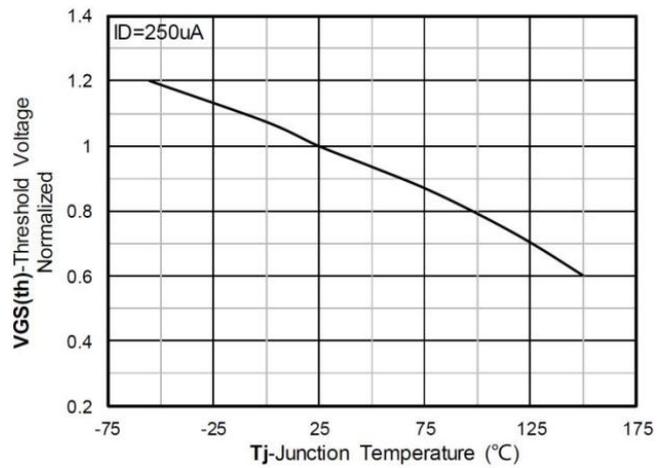
$R_{DS(on)}$ VS Drain Current



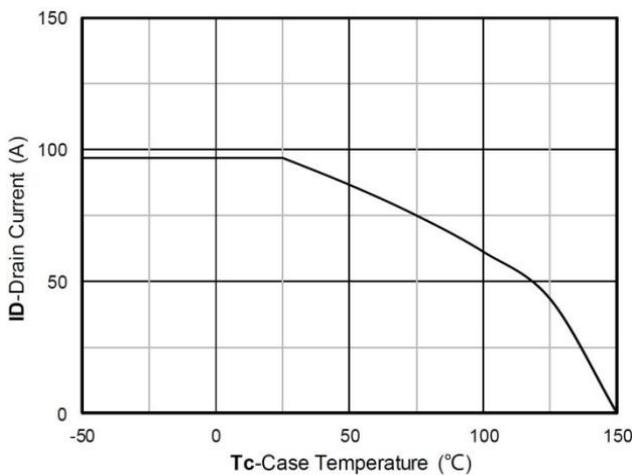
Forward characteristics of reverse diode



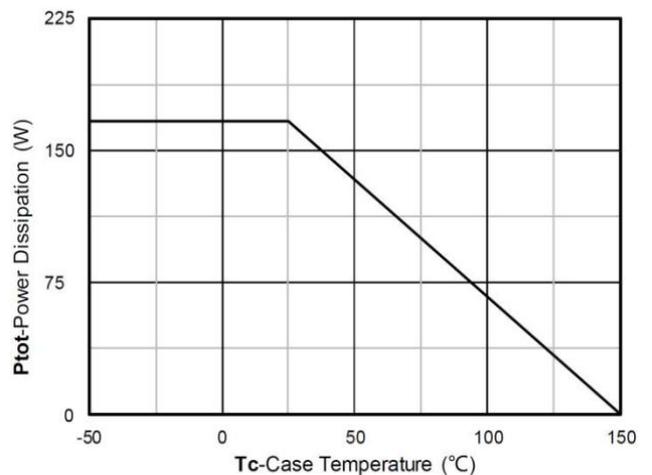
Normalized breakdown voltage



Normalized Threshold voltage

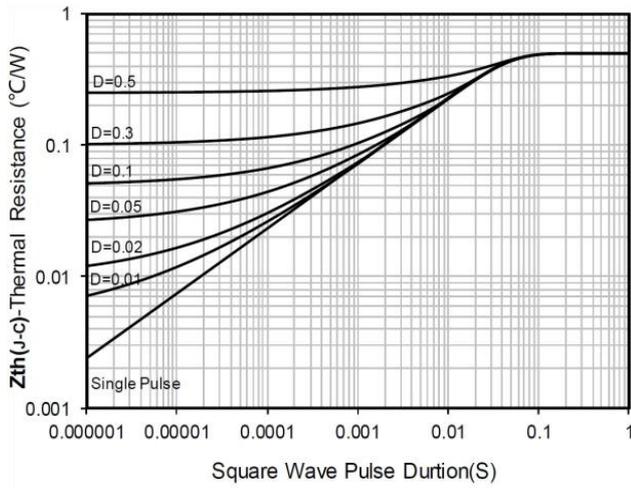


Current dissipation

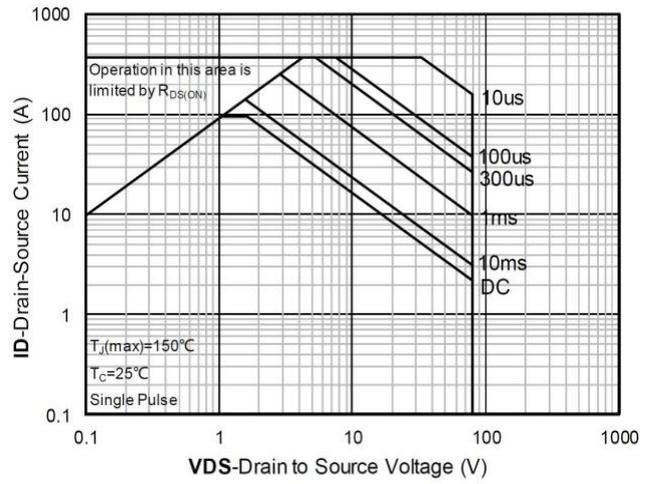


Power dissipation

Typical Characteristics

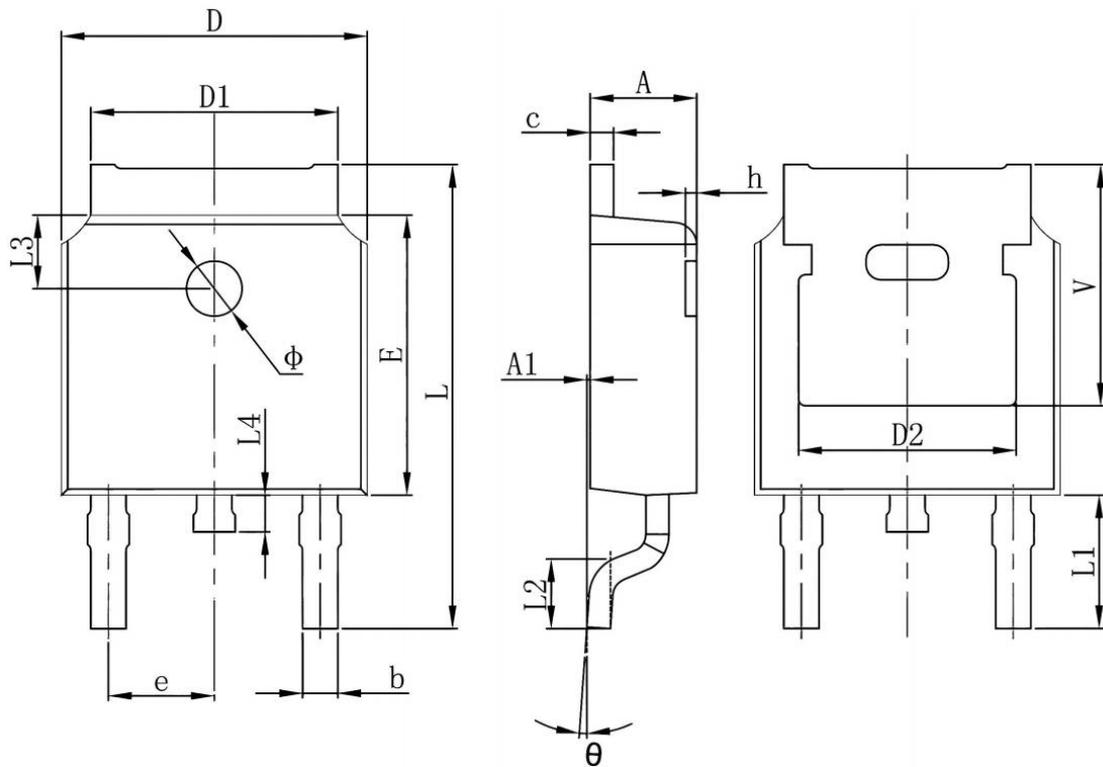


Maximum Transient Thermal Impedance



Safe Operation Area

TO-252AB Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 REF.		0.211 REF.	